



## Customer Information Notification

### 202306045I : NXP ATTJ Automated Packing Implementation for Tape and Reel Products

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Jul 05, 2023 **Effective date:** Jul 24, 2023

Here is your personalized notification about a NXP general announcement. For detailed information we invite you to [view this notification online](#)

#### Management summary

NXP Semiconductors announces the implementation of automated packing tools utilized during the final product packing and shipping activity at NXP ATTJ Tianjin, China, for the tape and reel configuration products associated with this notification.

#### Change Category

- |  |   |   |   |   |
|--|---|---|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process   | <input type="checkbox"/> Product Marking                      | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification             | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location  | <input checked="" type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Electrical spec./Test coverage |
| <input type="checkbox"/> Firmware            | <input type="checkbox"/> Other              |   |   |   |

## PCN Overview Description

NXP Semiconductors announces the implementation of automated packing tools utilized during the final product packing and shipping activity at NXP ATTJ Tianjin, China, for the tape and reel configuration products associated with this notification. The new automated tool packing process will result in operational efficiencies while maintaining processing quality.

Currently at ATTJ pack and ship step, products receive QA ink stamp at three different locations: reel label, moisture barrier bag (MBB) label, and box label. With automated packing tool implementation, products will receive QA ink stamp only on the reel label - no QA ink stamp on moisture barrier bag label or box label.

Automated packing tools utilize a series of cameras to closely monitor the packing process, reducing variability and ensuring quality. There are absolutely no changes to the NXP product or packing and shipping materials, other than the absence of QA ink stamps on moisture barrier bag and box labels.

As the ATTJ automated packing tools are brought online, there will be mixed usage of packing methods (current manual processing and new automated processing), which will result in mixed QA ink stamp label methodology on customer received final products. Be assured, the absence of QA ink stamps on moisture barrier bag and box labels do not mean the absence of quality at these steps.

Customer Information Notification 202306045I is issued to ensure no customer manufacturing disruptions upon NXP ATTJ implementation of new automated packing tool processing for the tape and reel configuration products associated with this notification. Upon notification Effective Date (anticipated 24Jul2023), NXP will begin a ramped implementation of automated packing shipments to customers with new QA ink stamp label process: seal date after implementation date results in no QA ink stamps on moisture barrier bag or box labels.

Please see the NXP ATTJ Automated Packing Change Summary attachment for packing tool process details.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PS-04.

**Reason**

The NXP ATTJ new automated tool packing process will result in operational efficiencies while maintaining processing quality.

**Identification of Affected Products**

QA ink stamp absence on moisture barrier bag and box labels after CIN 202306045I Effective Date identifies new automated packing tool processed material.

**Anticipated Impact on Form, Fit, Function, Reliability or Quality**

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No Impact on form, fit, function, reliability or quality (except as described for QA ink stamp absence on moisture barrier bag and box labels).

**Additional information**

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Additional documents: [view online](#)

**Contact and Support**

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For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

**About NXP Semiconductors**

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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